
Surface Mount Smart Card Connector

1. SCOPE

1.1. Content

This specification covers performance, tests and quality requirements for the Tyco Electronics Surface Mount (SMT) Smart Card connector. This connector is designed for surface mount technology and is available with 6 or 8 data contacts and 2 switch contacts and will accept ISO 7810-7816 type smart cards. The connector can be supplied without a cover and is also available in a contact module without card control. Contact modules are available with 6 or 8 data contacts and the option of switch contacts.

1.2. Qualification

When tests are performed on the subject product line, procedures specified in Figure 1 shall be used. All inspections shall be performed using the applicable inspection plan and product drawing.

1.3. Qualification Test Results

Successful qualification testing on the subject product line was completed on 26Mar01. The Qualification Test Report number for this testing is 501-506. This documentation is on file at and available from Engineering Practices and Standards (EPS).

2. APPLICABLE DOCUMENTS

The following documents form a part of this specification to the extent specified herein. Unless otherwise specified, the latest edition of the document applies. In the event of conflict between the requirements of this specification and the product drawing, the product drawing shall take precedence. In the event of conflict between the requirements of this specification and the referenced documents, this specification shall take precedence.

2.1. Tyco Electronics Documents

- 109-197: AMP Test Specifications vs EIA and IEC Test Methods
- 501-506: Qualification Test Report

2.2. Commercial Standard

EIA-364: Electrical Connector/Socket Test Procedures Including Environmental Classifications

3. REQUIREMENTS

3.1. Design and Construction

Product shall be of the design, construction and physical dimensions specified on the applicable product drawing.

3.2. Materials

Materials used in the construction of this product shall be as specified on the applicable product drawing.

3.3. Ratings

- Voltage: 30 volts AC
- Current: Signal application only
- Temperature: -40 to 90°C

3.4. Performance and Test Description

Product is designed to meet the electrical, mechanical and environmental performance requirements specified in Figure 1. Unless otherwise specified, all tests shall be performed at ambient environmental conditions per EIA-364.

3.5. Test Requirements and Procedures Summary

Test Description	Requirement	Procedure
Initial examination of product.	Meets requirements of product drawing.	EIA-364-18. Visual and dimensional (C of C) inspection per product drawing.
Final examination of product.	Meets visual requirements.	EIA-364-18. Visual inspection.
ELECTRICAL		
Termination resistance.	100 milliohms maximum.	EIA-364-23. Subject specimens to 100 milliamperes maximum and 20 millivolts maximum open circuit voltage. See Figure 3.
Insulation resistance.	1,000 megohms minimum.	EIA-364-21. Test between adjacent contacts. 500 volts DC.
Dielectric withstanding voltage.	750 volts AC at sea level for data contacts. 250 volts AC at sea level for switch contacts. 1 minute hold with no breakdown or flashover.	EIA-364-20, Condition I. Test between adjacent contacts.
MECHANICAL		
Solderability.	Solderable area shall have a minimum of 95% solder coverage.	EIA-638. Subject contacts to solderability.

Figure 1 (cont)

Test Description	Requirement	Procedure
Vibration, random.	No discontinuities of 1 microsecond or longer duration. See Note.	EIA-364-28, Test Condition VII, Condition D. Subject mated specimens to 3.10 G's rms between 20-500 Hz. 15 minutes in each of 3 mutually perpendicular planes. See Figure 4.
Mechanical shock.	No discontinuities of 1 microsecond or longer duration. See Note.	EIA-364-27, Method A. Subject mated specimens to 10 G's half-sine shock pulses of 11 milliseconds duration. 3 shocks in each direction applied along 3 mutually perpendicular planes, except 4 G's shock pulses in direction of card withdrawal, 18 total shocks. See Figure 4.
Durability.	See Note.	EIA-364-9. Mate and unmate specimens using PVC industry cards for 50,000 cycles at a maximum rate of 600 cycles per hour.
Mating force.	10 Newtons maximum.	EIA-364-13. Measure force necessary to mate specimens using PVC industry cards at a maximum rate of 12.7 mm [.5 in] per minute.
Unmating force.	1 Newton minimum.	EIA-364-13. Measure force necessary to unmate specimens using PVC industry cards at a maximum rate of 12.7 mm [.5 in] per minute.
ENVIRONMENTAL		
Thermal shock.	See Note.	EIA-364-32. Subject specimens to 5 cycles between -40 and 90°C.
Humidity-temperature cycling.	See Note.	EIA-364-31, Method III. Subject specimens to 10 cycles (10 days) between 25 and 65°C at 80 to 100% RH.
Temperature life.	See Note.	EIA-364-17, Method A, Test Condition 2, Test Time Condition D. Subject mated specimens to 70°C for 1000 hours.

Figure 1 (cont)

Test Description	Requirement	Procedure
Mixed flowing gas.	See Note.	EIA-364-65, Class IIA. Subject mated specimens to environmental Class IIA for 14 days.

NOTE

Shall meet visual requirements, show no physical damage, and meet requirements of additional tests as specified in the Product Qualification and Requalification Test Sequence shown in Figure 2.

Figure 1 (end)

3.6. Product Qualification and Requalification Test Sequence

Test or Examination	Test Group (a)				
	1	2	3	4	5
	Test Sequence (b)				
Initial examination of product	1	1	1	1	1
Termination resistance	3,7	2,4	2,4		
Insulation resistance				2,6	
Dielectric withstanding voltage				3,7	
Solderability					2
Vibration	5				
Mechanical shock	6				
Durability	4				
Mating force	2				
Unmating force	8				
Thermal shock				4	
Humidity-temperature cycling				5	
Temperature life		3(c)			
Mixed flowing gas			3(c)		
Final examination of product	9	5	5	8	3

NOTE

- (a) See paragraph 4.1.A.
(b) Numbers indicate sequence in which tests are performed.
(c) Precondition specimens with 10 cycles durability.

Figure 2

4. QUALITY ASSURANCE PROVISIONS

4.1. Qualification Testing

A. Specimen Selection

Specimens shall be prepared in accordance with applicable Instruction Sheets and shall be selected at random from current production. All test groups shall each consist of a minimum of 5 specimens. Test groups 1, 2, 3 and 5 shall each consist of a minimum of 5 specimens soldered to printed circuit boards. Test group 4 shall consist of a minimum of 5 unmounted specimens.

B. Test Sequence

Qualification inspection shall be verified by testing specimens as specified in Figure 2.

4.2. Requalification Testing

If changes significantly affecting form, fit or function are made to the product or manufacturing process, product assurance shall coordinate requalification testing, consisting of all or part of the original testing sequence as determined by development/product, quality and reliability engineering.

4.3. Acceptance

Acceptance is based on verification that the product meets the requirements of Figure 1. Failures attributed to equipment, test setup or operator deficiencies shall not disqualify the product. If product failure occurs, corrective action shall be taken and specimens resubmitted for qualification. Testing to confirm corrective action is required before resubmittal.

4.4. Quality Conformance Inspection

The applicable quality inspection plan shall specify the sampling acceptable quality level to be used. Dimensional and functional requirements shall be in accordance with the applicable product drawing and this specification.

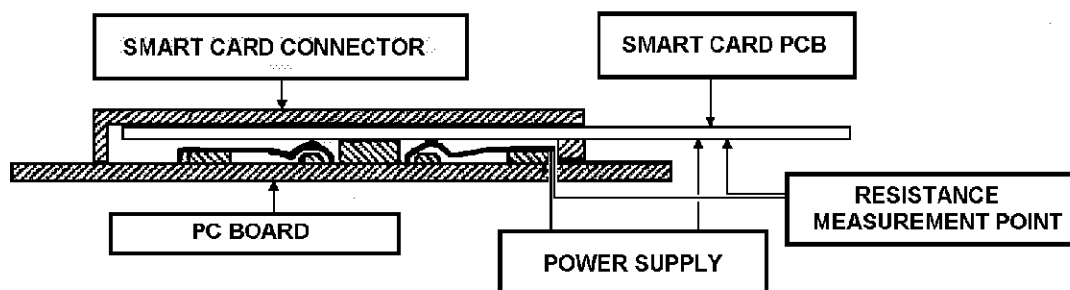


Figure 3
Termination Resistance Measurement Points

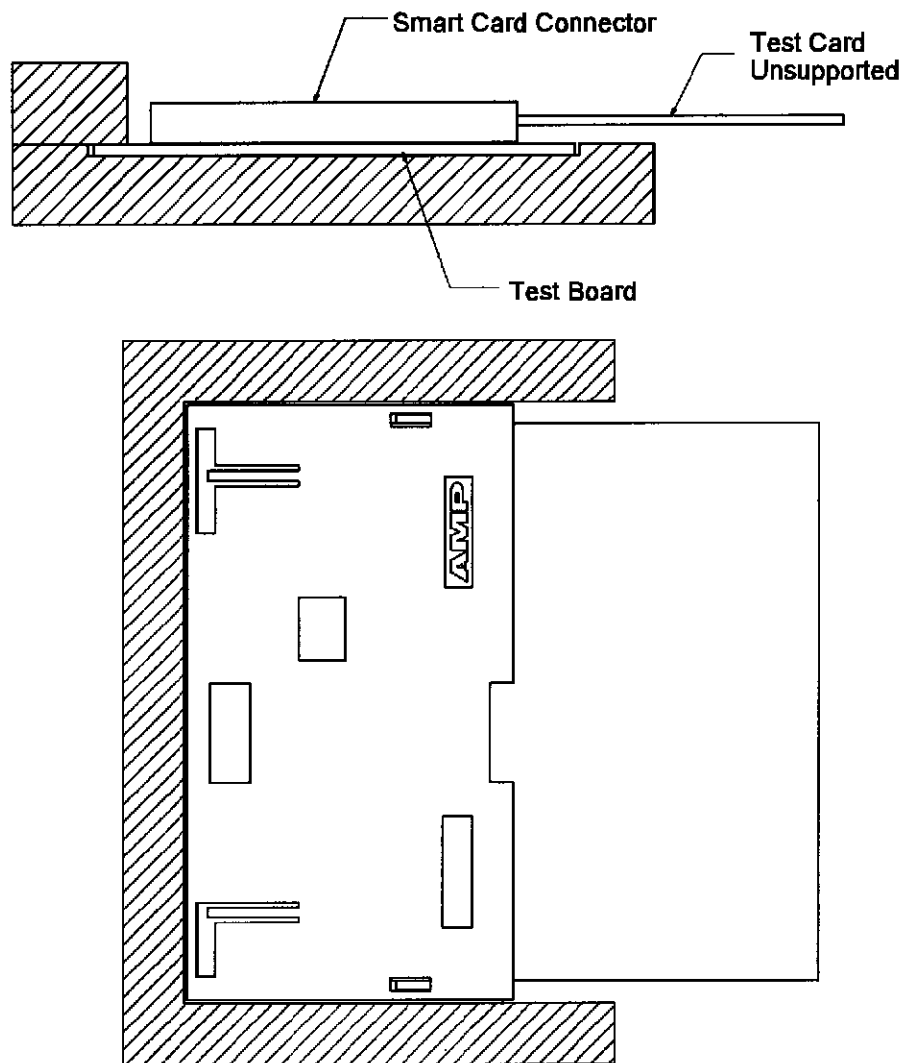


Figure 4
Vibration & Mechanical Shock Mounting Fixture